

# KetaSpire® KT-851 NL

## polyetheretherketone

KetaSpire® KT-851 NL resin is a depth-filtered grade of polyetheretherketone (PEEK) supplied in non-lubricated, natural-color pellet form and is specially designed for use in extruded wire insulation coating. KT-851 NL offers the needed balance of properties and processability for applying thin insulation coatings onto copper or other conducting wire using a continuous extrusion process to achieve a robust insulation coating that is capable of withstanding the harsh use environments of many industrial applications.

KetaSpire® PEEK is produced to the highest industry standards and is characterized by a distinct

combination of properties, which include excellent chemical resistance to organics, acids and bases, best in class fatigue resistance, excellent wear resistance, ease of melt processing and high purity.

A lubricated form of this resin is available as KT-851 in natural color (NT). The pellets in the lubricated versions are supplied with a very light dusting (0.01%) of calcium stearate to aid with conveying through single screw extruder-based processing equipment.

#### General

Across Flow

Water Absorption (24 hr)

Material Status	<ul> <li>Commercial: Active</li> </ul>		
Availability	<ul><li> Africa &amp; Middle East</li><li> Asia Pacific</li><li> Europe</li></ul>	<ul><li>Latin America</li><li>North America</li></ul>	
Additive	• Lubricant		
Features	<ul><li>Chemical Resistant</li><li>Ductile</li><li>Fatigue Resistant</li><li>Flame Retardant</li></ul>	<ul><li>Good Dimensional Stability</li><li>Good Impact Resistance</li><li>High Heat Resistance</li></ul>	
Uses	<ul><li>Electrical/Electronic Applications</li><li>Oil/Gas Applications</li></ul>	• Wire Jacketing	
Agency Ratings	• ISO 10993		
RoHS Compliance	<ul> <li>Contact Manufacturer</li> </ul>		
Appearance	<ul> <li>Natural Color</li> </ul>		
Forms	• Pellets		
Processing Method	<ul><li>Injection Molding</li><li>Machining</li></ul>	• Profile Extrusion	
Physical	Typical Value Unit		Test method
Density / Specific Gravity		1.30	ASTM D792
Melt Mass-Flow Rate (MFR) (400°C/2.16 kg)		10 g/10 min	ASTM D1238
Molding Shrinkage			ASTM D955
Flow	1.1	to 1.3 %	

1.3 to 1.5 %

0.10 %

ASTM D570

Mechanical	Typical Value	Unit	Test method
Tensile Modulus			
1	3600	MPa	ASTM D638
	3850	МРа	ISO 527-1/1A/1
Tensile Stress			
Yield	95.0	МРа	ISO 527-2/1A/50
	96.0	МРа	ASTM D638
Tensile Elongation			
Yield <sup>2</sup>	5.2	%	ASTM D638
Yield	4.8	%	ISO 527-2/1A/50
Break <sup>2</sup>	20 to 30	%	ASTM D638
Break	20 to 30	%	ISO 527-2/1A/50
Flexural Modulus			
	3900	МРа	ASTM D790
	3620	МРа	ISO 178
Flexural Strength			
	152	МРа	ASTM D790
	112	МРа	ISO 178
Compressive Strength	121	MPa	ASTM D695
Shear Strength	91.5	MPa	ASTM D732
Impact	Typical Value	Unit	Toot mothed
Impact Notched Izod Impact	Typical Value	Unit	Test method
	60	J/m	ASTM D256
		kJ/m²	ISO 180
	7.5	KJ/III	
Unnotched Izod Impact	No Break		ASTM D4812 ISO 180
Hardness	Typical Value	Unit	Test method
Rockwell Hardness (M-Scale)	97		ASTM D785
Durometer Hardness (Shore D, 1 sec)	88		ASTM D2240
The arrest of	True is all Maline	T I with	To all you also and
Thermal  Deflection Tenanguature Under Lead 3	Typical Value	Unit	Test method
Deflection Temperature Under Load <sup>3</sup>	157	00	ASTM D648
1.8 MPa, Annealed, 3.20 mm	157		4071450410
Glass Transition Temperature	150		ASTM D3418
Peak Melting Temperature	340		ASTM D3418
CLTE - Flow (-50 to 50°C)	4.3E-5	cm/cm/°C	ASTM E831
Specific Heat		. 1 1	DSC
50°C		J/kg/°C	
200°C	1950	J/kg/°C	
Thermal Conductivity	_	W/m/K	ASTM E831

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Electrical	Typical Value Unit	Test method
Surface Resistivity	> 1.9E+17 ohms	ASTM D257
Volume Resistivity	2.5E+17 ohms·cm	ASTM D257
Dielectric Strength		ASTM D149
0.0500 mm, Amorphous Film	200 kV/mm	
Fill Analysis	Typical Value Unit	Test method
Melt Viscosity (400°C, 1000 sec^-1)	380 Pa·s	ASTM D3835

#### Additional Information

#### Standard Packaging and Labeling

• KetaSpire resins are packaged in polyethylene buckets or cardboard boxes depending upon the order size. Individual packages will be plainly marked with the product, color, lot number, and net weight.

Injection	Typical Value Unit	
Drying Temperature	150 °C	
Drying Time	4.0 hr	
Rear Temperature	355 °C	
Middle Temperature	365 °C	
Front Temperature	370 °C	
Nozzle Temperature	375 °C	
Mold Temperature	175 to 205 °C	
Injection Rate	Fast	
Screw Compression Ratio	2.5:1.0 to 3.5:1.0	

#### Injection Notes

#### Drying

• KetaSpire resins must be dried completely prior to melt processing. Incomplete drying will result in defects in the formed part ranging from surface streaks to severe bubbling. Pellets can be dried on trays in a circulating air oven or in desiccating hopper dryer. Drying conditions recommended are 4 hours at 150°C (300°F).

#### Injection Molding

• KetaSpire resins can be readily injection molded in most screw injection machines. A general purpose screw with a compression ratio in the range of 2.5 - 3.5:1 is recommended, as is minimum back pressure. Injection speeds should be as fast as possible, consistent with part appearance requirements. Mold temperatures in the range of 175°C to 205°C (350°F to 400°F) are suggested. Recommended starting point barrel temperatures are shown in the following table.

#### Notes

Typical properties: these are not to be construed as specifications.

- <sup>1</sup> 1.0 mm/min
- <sup>2</sup> 50 mm/min
- <sup>3</sup> 2 hours at 200°C

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### www.syensqo.com

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